

Chemicals contained in products

Package-type

Epson Package name; **QFP21-176PIN / Halogen free**

JEITA Package name; **P-LQFP176-2424-0.50**

Lead frame plating; **Lead(Pb) Free**

Weight; **1.96 [g]** *Note1

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	35.9	Silicon	7440-21-3	35.9	999894	Base material
			Boron	7440-42-8	0.0001	2	Dopant
			Phosphorus	7723-14-0	0.0002	5	Dopant
			Aluminum	7429-90-5	0.001	20	Metalization
			Arsenic *Note3	7440-38-2	0.0002	5	Dopant
			Fluorine *Note3	7782-41-4	0.0001	2	Dopant
			Titanium *Note3	7440-32-6	0.001	20	Metalization
			Molybdenum *Note3	7439-98-7	0.0007	20	Metalization
			Tungsten *Note3	7440-33-7	0.001	30	Metalization
			Cobalt *Note3	7440-48-4	0.0001	2	Metalization
	Stress buffer coat	0.72	Polyimide	-	0.72	1000000	Stress buffer coat *Note4
Package	Die Bonding material	3.59	Silver	7440-22-4	2.30	640000	Base material
			Epoxy resin	-	0.73	205000	Adhesive
			Phenol resin	-	0.28	80000	Adhesive
			Inorganic powder	-	0.18	48000	Additive
			Bismuth compound	-	0.10	27000	Ion trap
	Lead Frame Plating	21.90	Tin	7440-31-5	21.90	1000000	Solder
	Lead Frame	437.50	Copper	7440-50-8	413.50	945000	Conductor
			Silver	7440-22-4	2.10	5000	Inner lead plating
			Others *Note5	-	21.90	50000	Additive
	Bonding Wire	3.10	Gold	7440-57-5	3.10	1000000	Conductor
	Mold resin	1457.29	Epoxy resin	-	72.86	50000	Base material
			Silica	60676-86-0/-	1318.85	905000	Filler
			Carbon black	1333-86-4	7.29	5000	Coloring agent
			Hardening chemical(ex:Phenol resin)	-	58.29	40000	Base material

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

*Note4 The stress buffer coat may not be used depending on the individual model.

*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included.